# MSKSEMI 美森科







TVC



TSS



MOV



GDT



PIFD

# BAS21/A/C/S

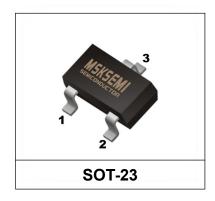
**Product specification** 



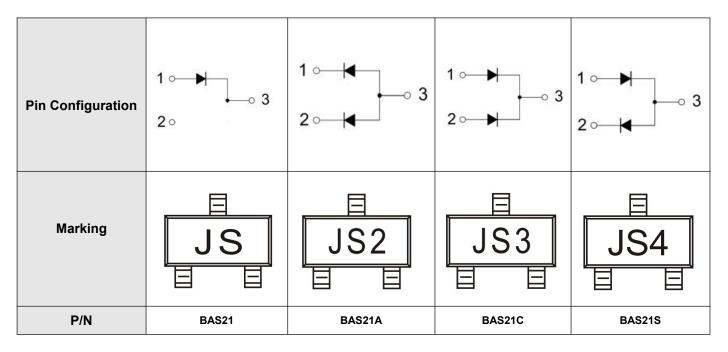


#### **Features**

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance



#### **Reference News**





## Maximum Ratings @Ta=25℃

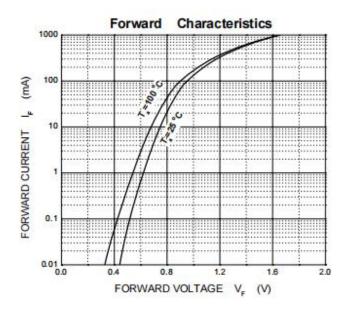
Parameter	Symbol	Limit	Unit
Repetitive peak reverse voltage	V <sub>RRM</sub>		
Working peak reverse voltage	V <sub>RWM</sub>	250	V
DC blocking voltage	V <sub>R</sub>		
Forward continuous current	I <sub>FM</sub>	400	mA
Average rectified output current	lo	200	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I <sub>FSM</sub>	2.5	А
Repetitive peak forward surge current	I <sub>FRM</sub>	625	mA
Power dissipation	PD	225	mW
Thermal resistance junction to ambient	Reja	555	°C/W
Junction temperature	TJ	150	°C
Storage temperature range	Tstg	-55~+150	°C

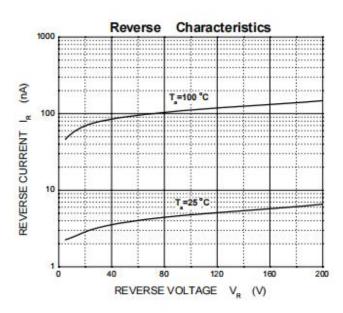
# ELECTRICAL CHARACTERISTICS (Ta=25 $^{\circ}$ C unless otherwise specified)

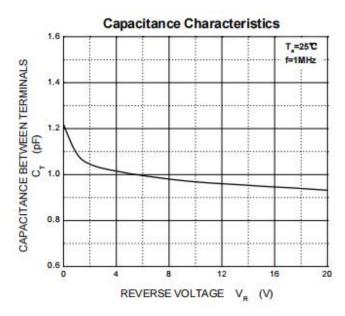
Parameter	Symbol	Test conditions	Min	Max	Unit
Reverse breakdown voltage	V <sub>(BR)</sub>	I <sub>R</sub> = 100μA	250		V
Reverse voltage leakage current	I <sub>R</sub>	V <sub>R</sub> = 200V		0.1	μΑ
Forward voltage	VF	I <sub>F</sub> =100mA		1000	mV
		I <sub>F</sub> =200mA		1250	IIIV
Diode capacitance	CD	V <sub>R</sub> =0V, f=1MHz		5	pF
Reveres recovery time	t <sub>rr</sub>	I <sub>F</sub> =I <sub>R</sub> =30mA,I <sub>rr</sub> =0. 1×I <sub>R</sub> , R <sub>L</sub> =100 Ω		50	ns

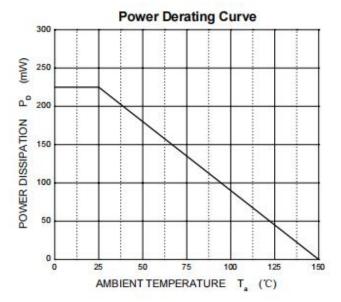


### **Typical Characteristics**



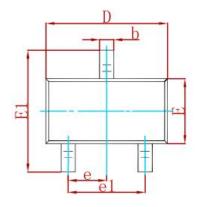


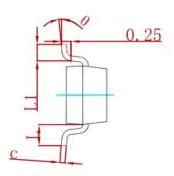


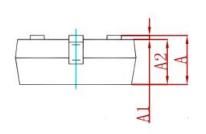




#### PACKAGE MECHANICAL DATA

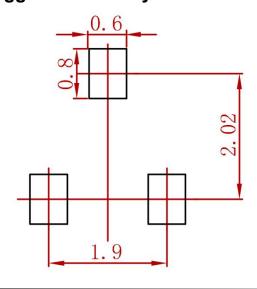






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
BAS21/A/C/S	SOT-23	3000



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